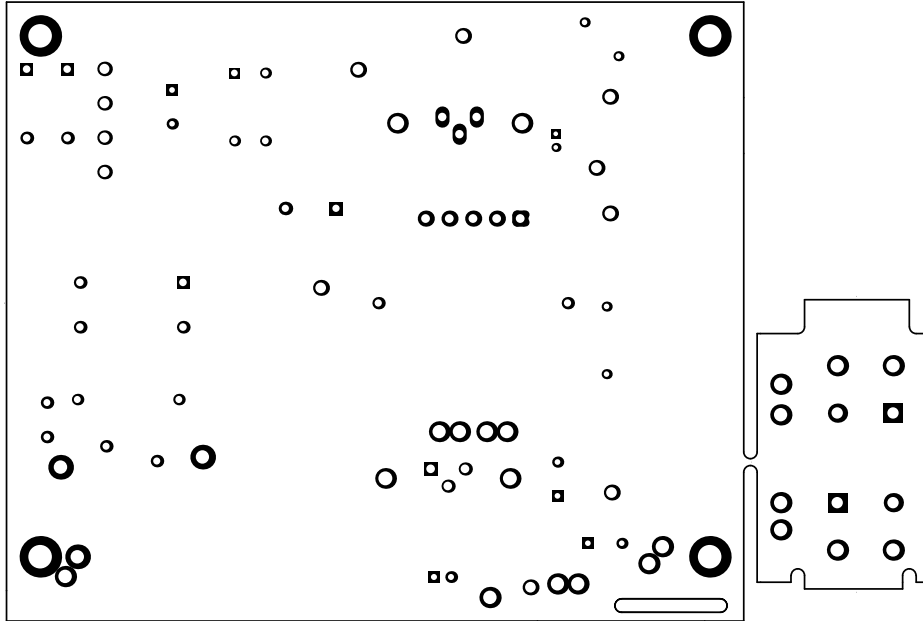
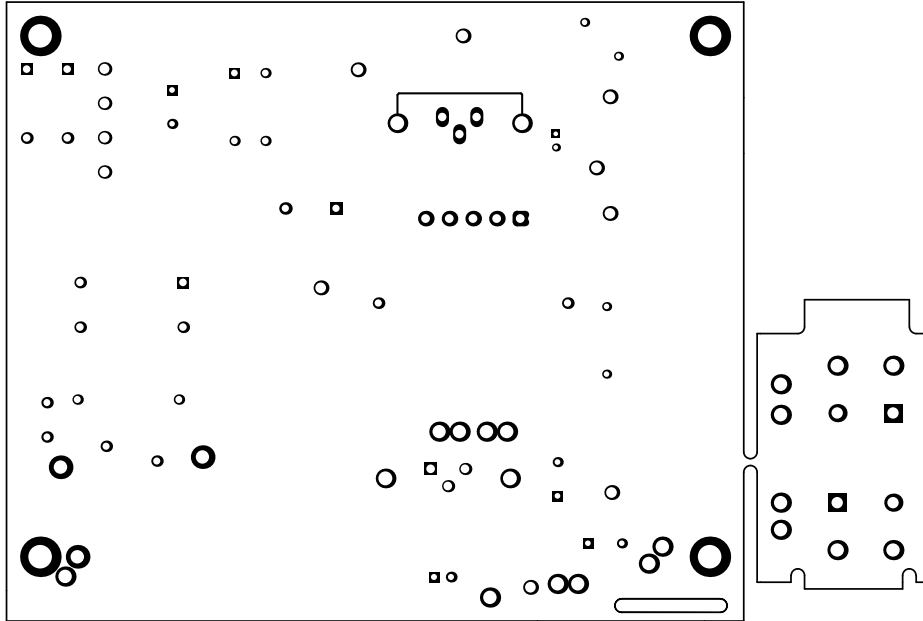


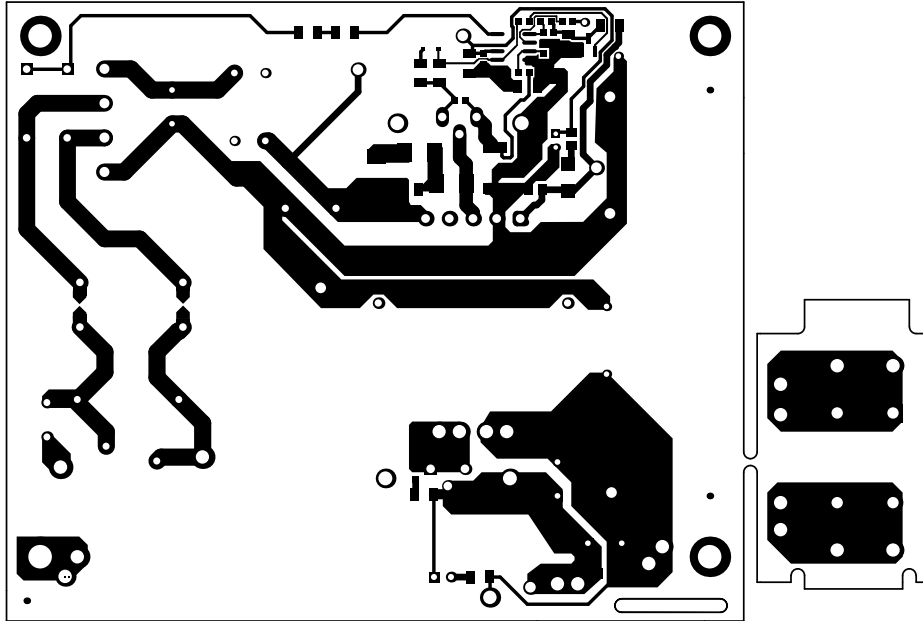
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 15/04/2014 09:50:54	TEXAS INSTRUMENTS	



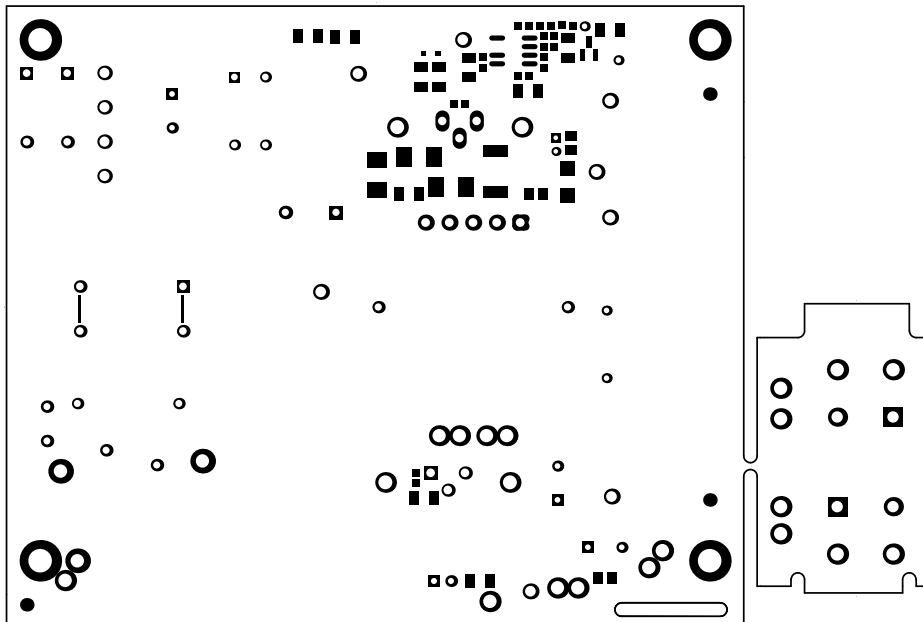
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 15/04/2014 09:50:55	TEXAS INSTRUMENTS	



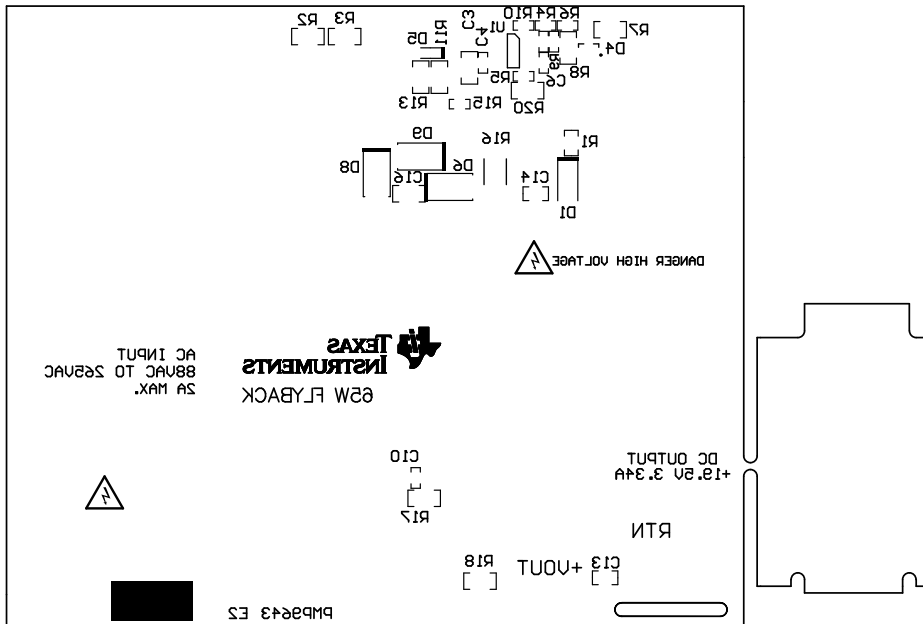
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 15/04/2014 09:50:55	TEXAS INSTRUMENTS	



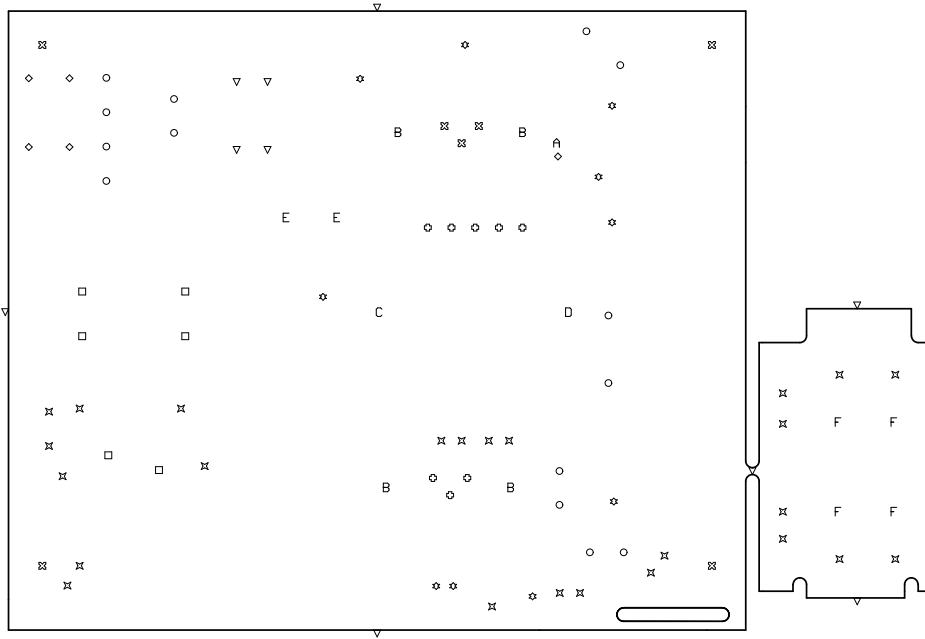
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 15/04/2014 09:50:56	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 15/04/2014 09:50:56	TEXAS INSTRUMENTS	



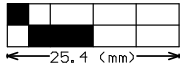
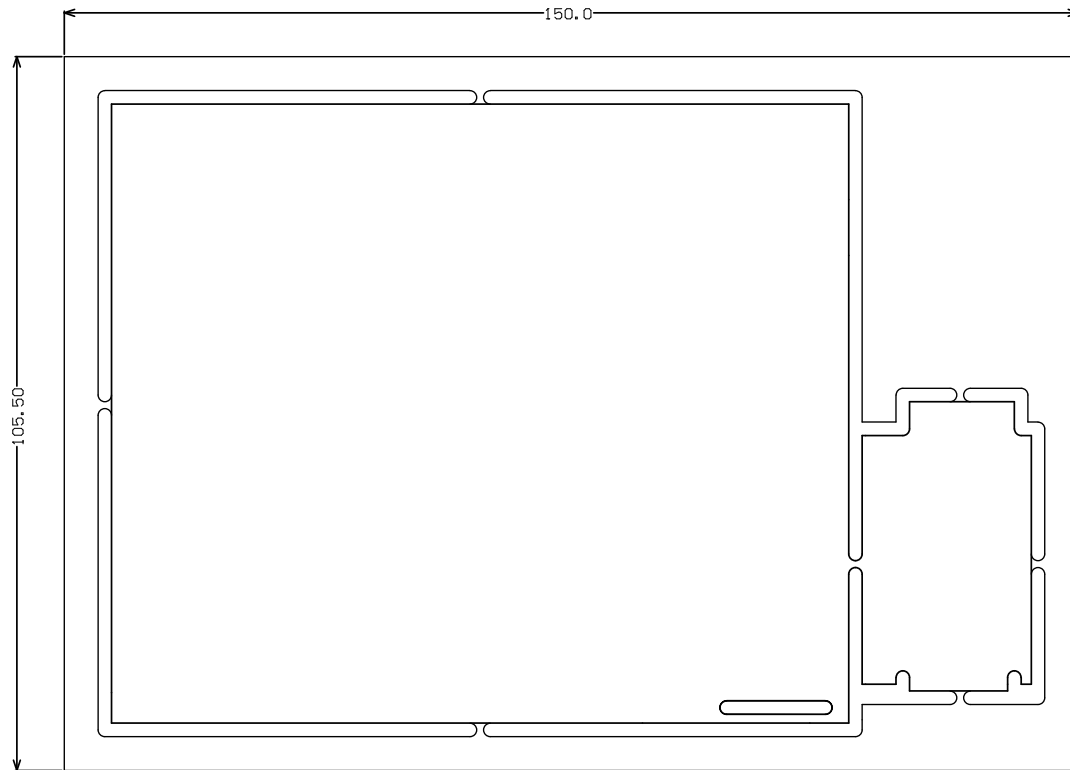
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 15/04/2014 09:50:57	TEXAS INSTRUMENTS	



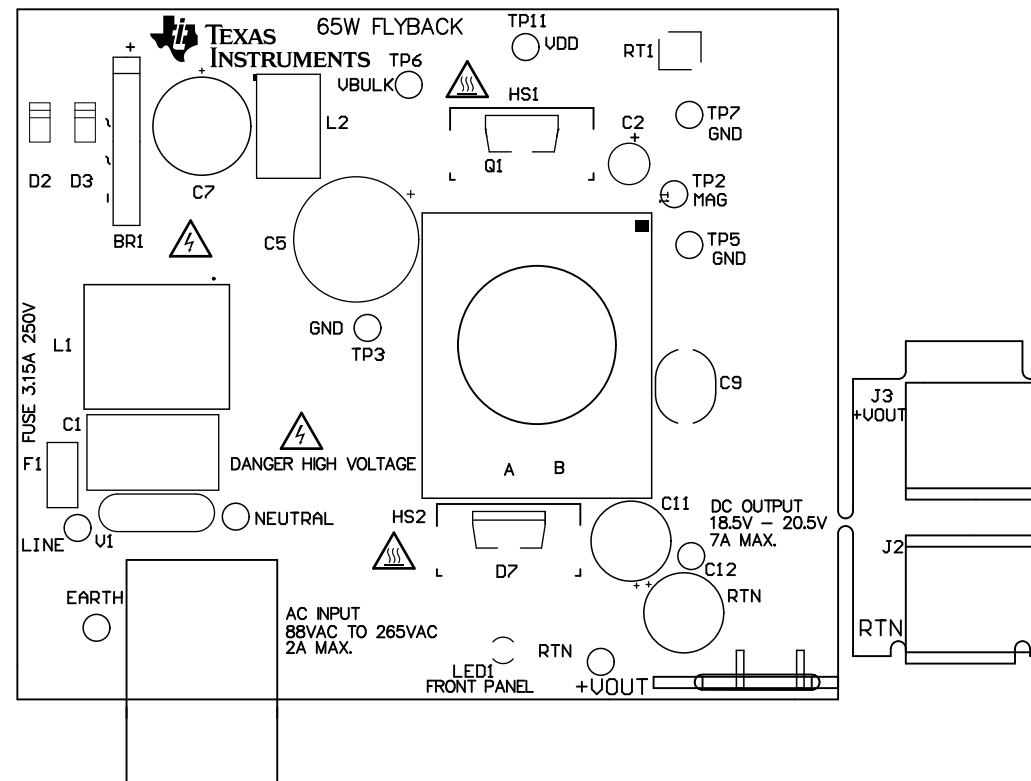
Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	7	0.5mm (19.685mil)	NPTH	Round
A	1	0.711mm (28mil)	PTH	Round
◇	1	0.712mm (28.012mil)	PTH	Round
○	10	0.85mm (33.465mil)	PTH	Round
*	2	0.914mm (35.984mil)	PTH	Round
▽	4	1.016mm (40mil)	PTH	Round
⊗	4	1.05mm (41.339mil)	PTH	Round
□	2	1.067mm (42mil)	PTH	Round
C	1	1.092mm (42.992mil)	PTH	Round
D	1	1.092mm (43mil)	PTH	Round
E	2	1.1mm (43.307mil)	PTH	Round
◇	4	1.15mm (45.276mil)	PTH	Round
□	4	1.151mm (45.3mil)	PTH	Round
⊗	3	1.27mm (50mil)	PTH	Round
⊗	3	1.3mm (51.181mil)	PTH	Round
⊗	5	1.321mm (52mil)	PTH	Round
○	4	1.5mm (59.055mil)	PTH	Round
*	8	1.6mm (63mil)	PTH	Round
F	4	1.7mm (66.929mil)	PTH	Round
⊗	21	2mm (78.74mil)	PTH	Round
B	4	2.083mm (82mil)	PTH	Round
⊗	4	3.5mm (137.795mil)	PTH	Round
99 Total				

Drill Table

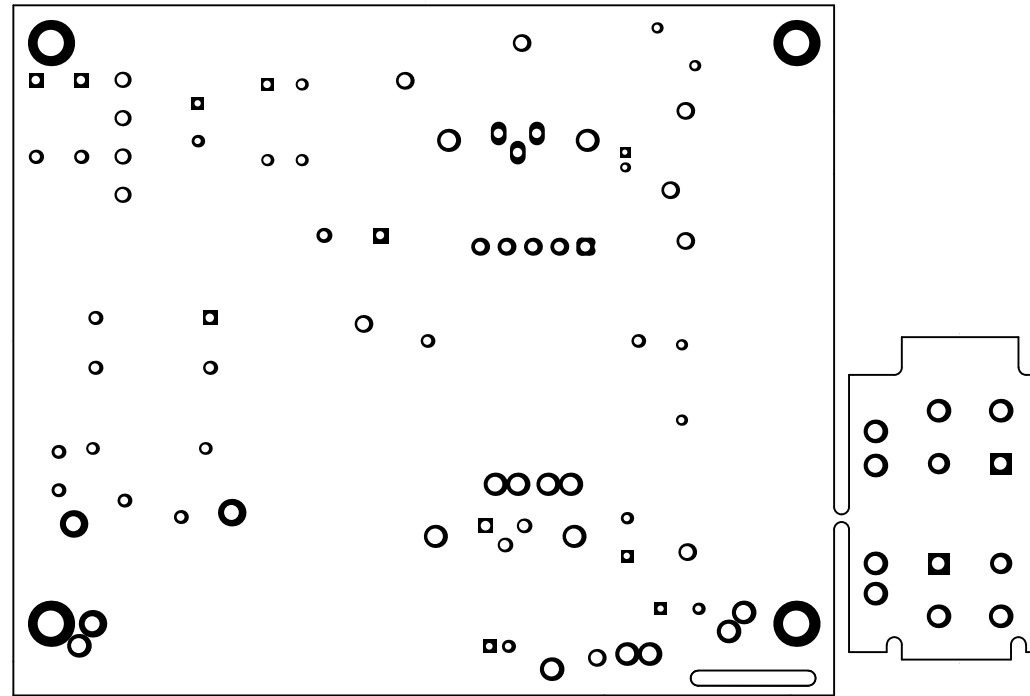
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 15/04/2014 09:50:57	TEXAS INSTRUMENTS	



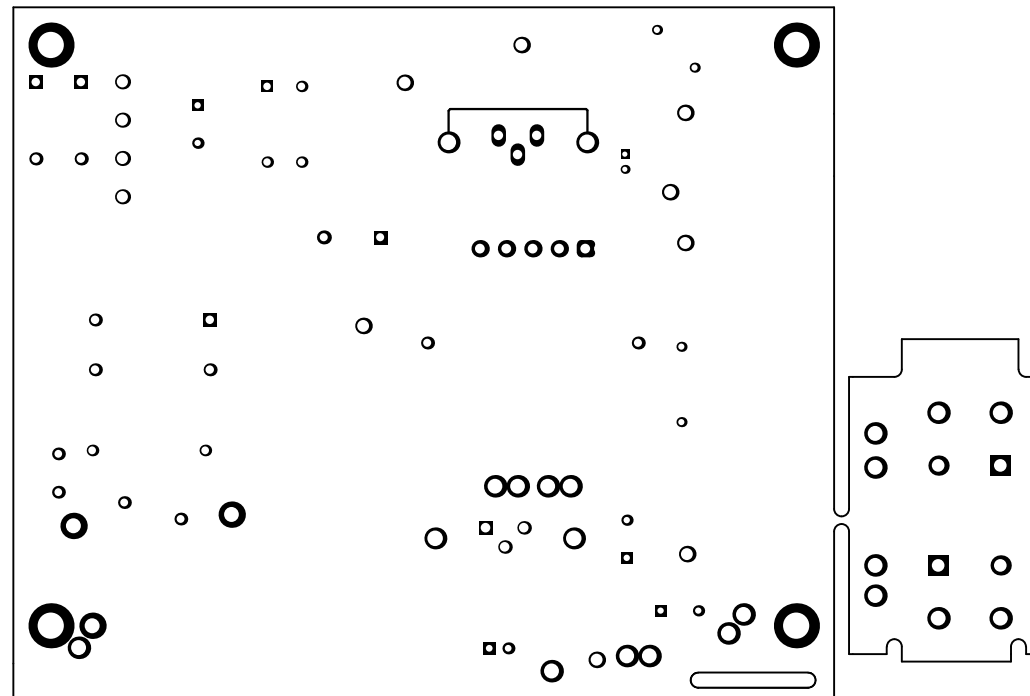
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 15/04/2014 09:51:00	TEXAS INSTRUMENTS	



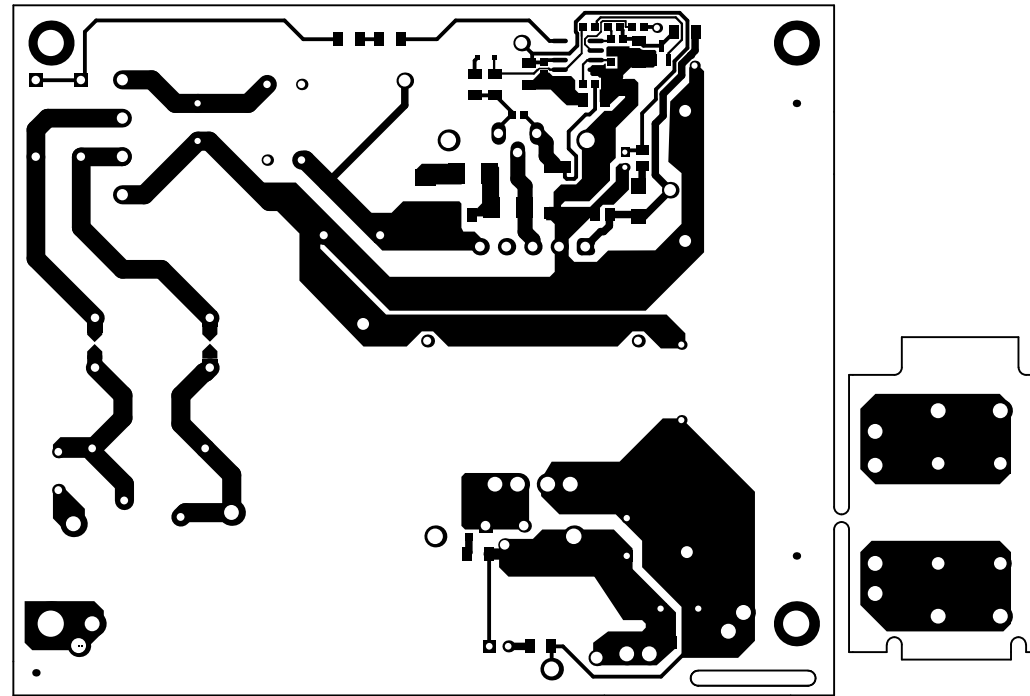
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 15/04/2014 09:51:01	TEXAS INSTRUMENTS	



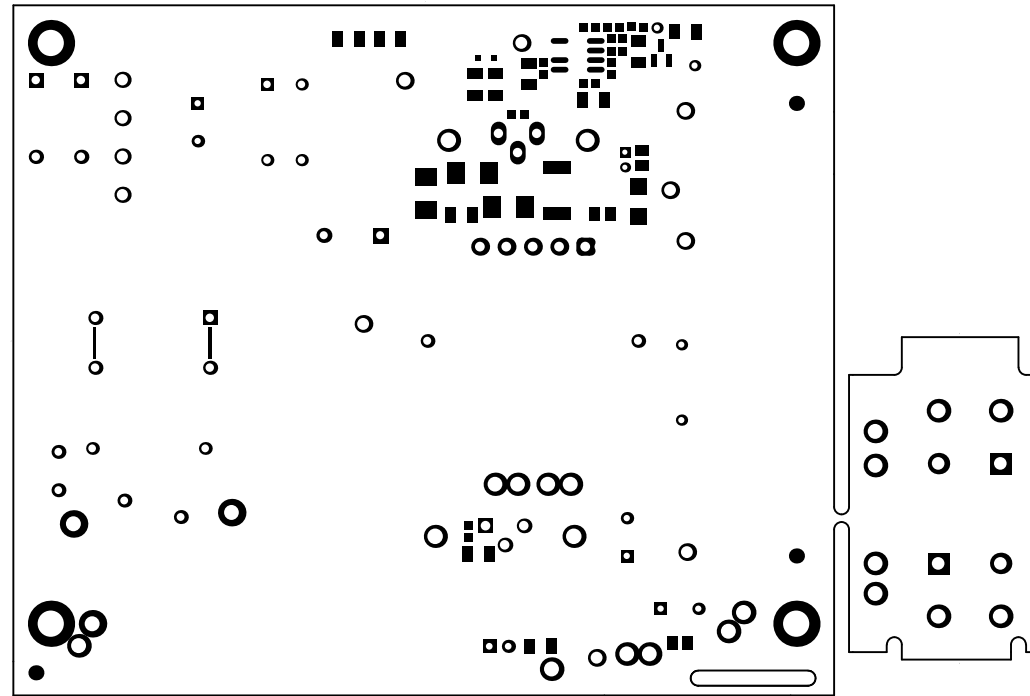
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 15/04/2014 09:51:01	TEXAS INSTRUMENTS	



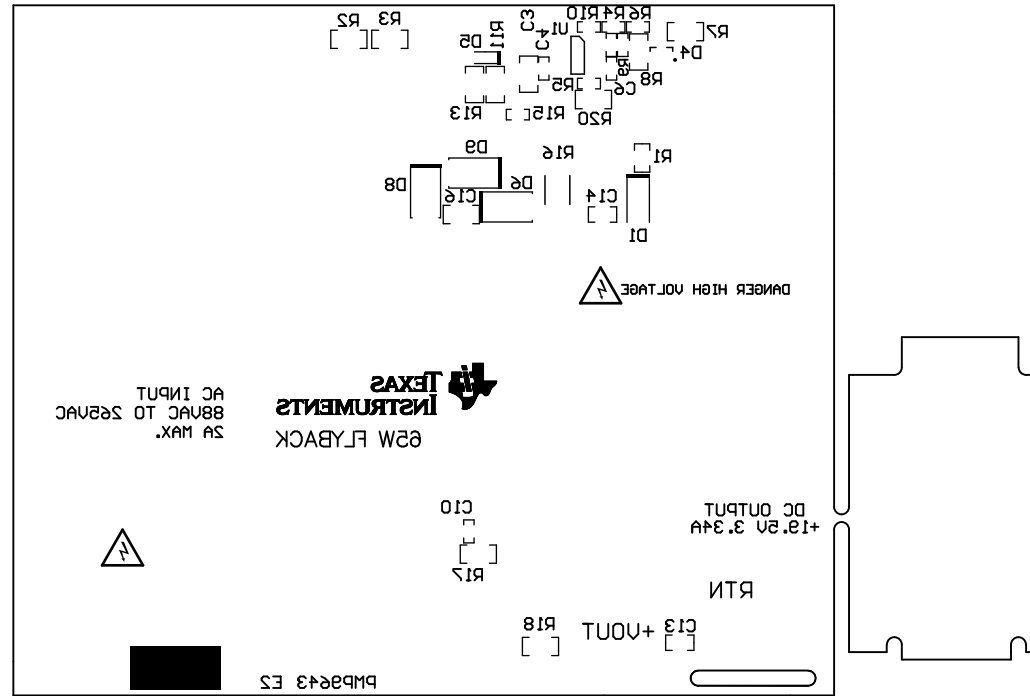
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 15/04/2014 09:51:02	TEXAS INSTRUMENTS	



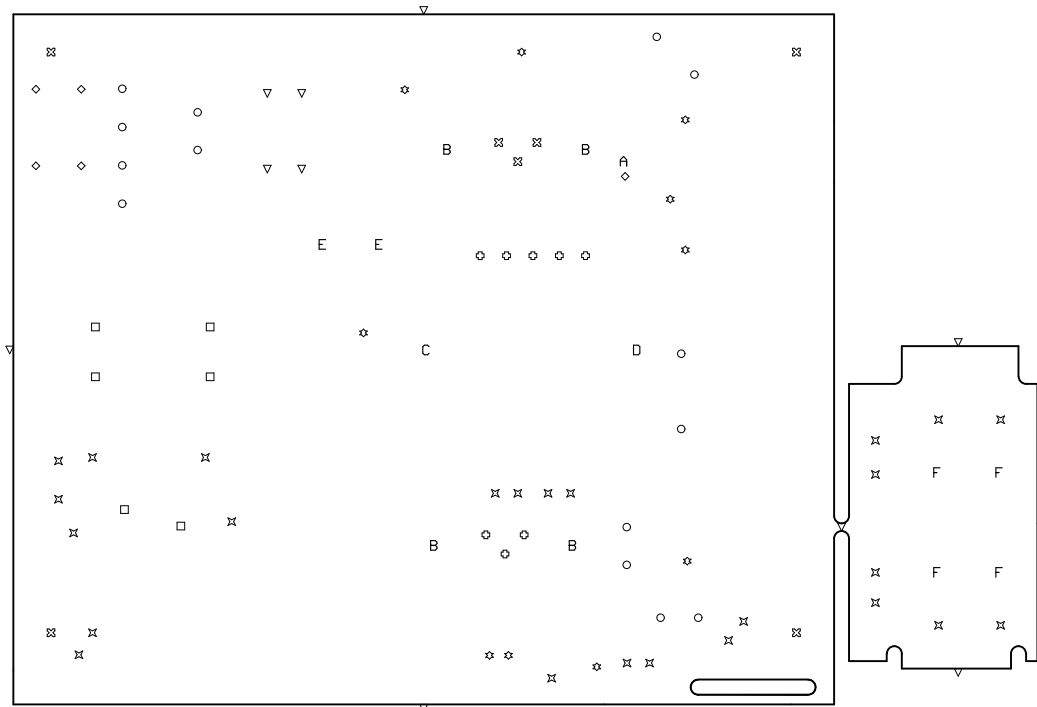
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 15/04/2014 09:51:02	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 15/04/2014 09:51:03	TEXAS INSTRUMENTS	



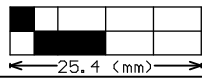
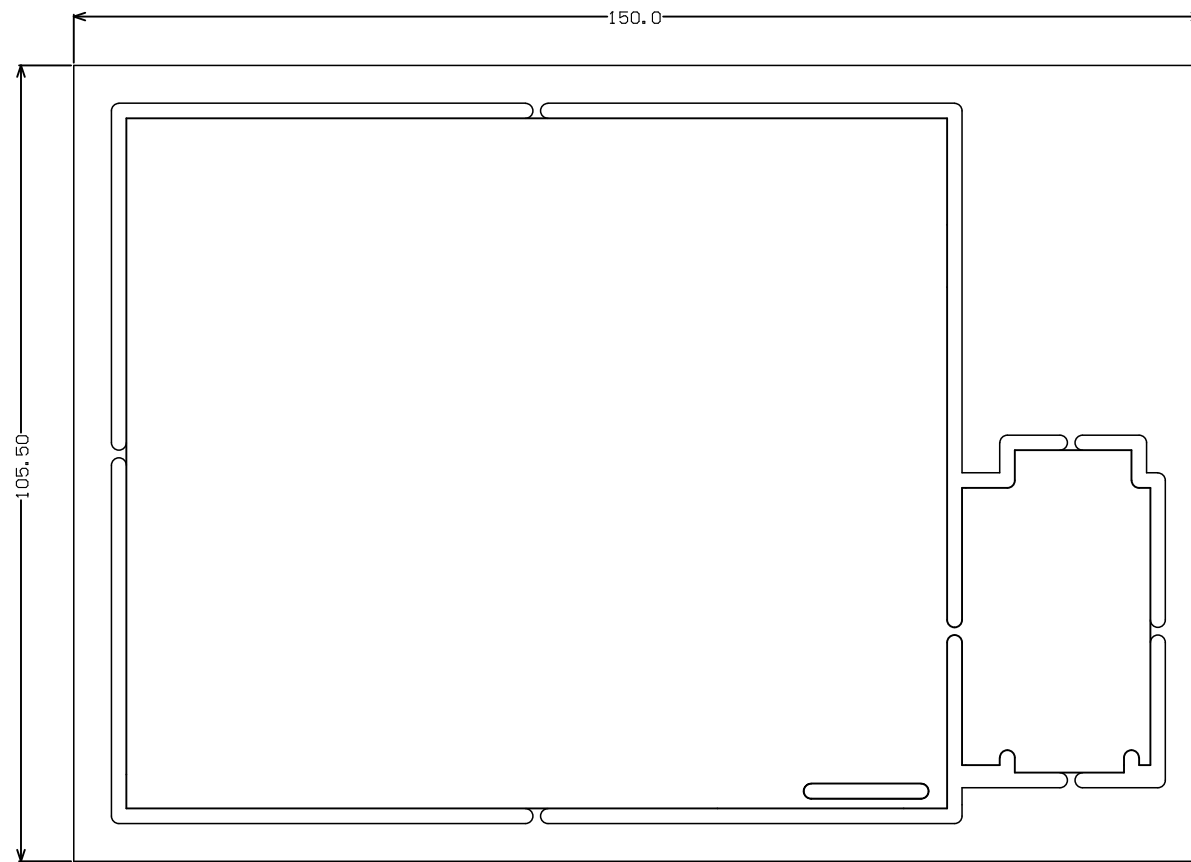
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 15/04/2014 09:51:03	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
▽	7	0.5mm (19.685mil)	NPTH	Round
A	1	0.711mm (28mil)	PTH	Round
◇	1	0.712mm (28.012mil)	PTH	Round
○	10	0.85mm (33.465mil)	PTH	Round
*	2	0.914mm (35.984mil)	PTH	Round
▽	4	1.016mm (40mil)	PTH	Round
×	4	1.05mm (41.339mil)	PTH	Round
□	2	1.067mm (42mil)	PTH	Round
C	1	1.092mm (42.992mil)	PTH	Round
D	1	1.092mm (43mil)	PTH	Round
E	2	1.1mm (43.307mil)	PTH	Round
◇	4	1.15mm (45.276mil)	PTH	Round
□	4	1.151mm (45.3mil)	PTH	Round
⊗	3	1.27mm (50mil)	PTH	Round
⊙	3	1.3mm (51.181mil)	PTH	Round
⊙	5	1.321mm (52mil)	PTH	Round
○	4	1.5mm (59.055mil)	PTH	Round
*	8	1.6mm (63mil)	PTH	Round
F	4	1.7mm (66.929mil)	PTH	Round
×	21	2mm (78.74mil)	PTH	Round
B	4	2.083mm (82mil)	PTH	Round
⊗	4	3.5mm (137.795mil)	PTH	Round
	99	Total		

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 15/04/2014 09:51:04	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9643	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 15/04/2014 09:51:43	TEXAS INSTRUMENTS	

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